2026 IEEE 18th International Conference on Solid-State and Integrated Circuit Technology (ICSICT)

Oct. 27 - 30, 2026 | Hangzhou, China

Sponsorship Program Overview

2026 IEEE 18th International Conference on Solid-State and Integrated Circuit Technology (ICSICT 2026)

2026 IEEE 18th International Conference on Solid-State and Integrated Circuit Technology (ICSICT) in the series aiming to provide an international forum for the presentation and discussion of recent advances in solid-state and integrated circuit technology. The conference will be held on Oct. 27 - 30, 2026 in Hangzhou, China. All aspects of solid-state digital IC & system level design, analog, devices, process technologies and other related research are within the scope of the conference. Over the course of four days, a rich program of contributed and invited presentations will cover the latest advancements in various fields. These presentations will be delivered through both oral and poster sessions, accompanied by panel discussions addressing cutting-edge technology issues and various engaging activities. This comprehensive program aims to foster extensive opportunities for the exchange of technical information and create a stimulating atmosphere for mutual communication among all participants. The presentation of the Excellent Student Paper Award and the Outstanding Young Scholar Paper Award will take place during the conference's closing ceremony. Enterprises with relevance to the event are encouraged to join and actively take part in the exhibition.

Platinum Sponsorship (80,000 RMB)

- **2 exhibition booths outside the venue**
- **Company logo featured as the title sponsor on the conference backdrop and promotional materials**
- **3 complimentary conference passes (accommodation not included)**
- **5-minute product presentation following the keynote speech**
- **15-minute detailed product introduction during the Industrial Forum**

Gold Sponsorship (50,000 RMB)

- **1 exhibition booth outside the venue**
- **Company logo featured as the title sponsor on the conference backdrop and promotional materials**
- **2 complimentary conference passes (accommodation not included)**
- **15-minute detailed product introduction during the Industrial Forum**

Silver Sponsorship (20,000 RMB)

- **1 exhibition booth outside the venue**
- **Company logo featured as a title sponsor on the conference backdrop and promotional materials**
- **1 complimentary conference pass (accommodation not included)**

Exhibitor Sponsorship (5,000 / 8,000 RMB)

- ***Option 1*: 5,000 RMB**
- **1 exhibition booth (electricity not provided)**
- **1 complimentary conference pass (meals not included; accommodation not included)**
- ***Option 2*: 8,000 RMB**
- **1 exhibition booth (electricity provided)**
- **1 complimentary conference pass (accommodation not included)**

Cooperative Industry Media Sponsorship (Limited to 2 Companies)

- **1 exhibition booth outside the venue**
- **Company logo featured as a title sponsor on the conference backdrop and promotional materials**
- **1 complimentary conference pass (accommodation not included)**

Exclusive Banquet Sponsorship (100,000 RMB)

- **Exclusive sponsorship of the opening reception or closing banquet, organized by the host according to the sponsor's requirements**
- **10-minute speech by sponsor's representative during the banquet**
- **Company logo featured as a title sponsor on the conference backdrop and promotional materials**
- **2 exhibition booths outside the venue**
- **3 complimentary conference passes (accommodation not included)**
- **15-minute detailed product introduction during the Industrial Forum**

Integrated Circuit Design AI Agent Competition Track Title Sponsorship

To advance the application of the latest artificial intelligence technologies in the field of integrated circuits and showcase cutting-edge research achievements in IC design and design automation, the ICSICT Organizing Committee plans to host the Integrated Circuit Design AI Agent Competition (AI Agent for Integrated Circuit Design) concurrently with the conference. The competition is scheduled to include four tracks: Digital, Analog, RF, and Device. Competition topics are expected to be announced in January 2026. We sincerely invite domestic and international EDA companies and IC design enterprises to sponsor the competition, and also welcome technical experts from various companies to participate as members of the task-setting panel.

Track Title Sponsorship (30,000 RMB per track)

- **Participation in the selection and awarding of the sponsored track**
- **1 exhibition booth outside the venue**
- **1 complimentary conference pass (accommodation not included)**
- **Display of the sponsor's logo next to the corresponding track in the conference schedule**

Talent Recruitment Zone Sponsorship

To support the talent recruitment needs of universities, enterprises, and institutions, this conference has specially established a "Talent Recruitment Zone," providing organizations with opportunities for centralized display and face-to-face exchanges.

Talent Recruitment Zone Sponsorship (5,000 / 10,000 RMB)

- ***Option 1*: 5,000 RMB**
- **1 exhibition booth for placing promotional materials/recruitment information**
- **Organization name listed in the Talent Recruitment Zone display roster**
- **1 complimentary conference pass (meals not included, accommodation not included)**
- ***Option 2*: 10,000 RMB**
- **1 exhibition booth for placing promotional materials/recruitment information**
- **Organization name listed in the Talent Recruitment Zone display roster**
- **Exclusive use of 1 meeting room for recruitment interviews (available by reservation)**
- **1 complimentary conference pass (meals not included, accommodation not included)**

Note:
The standard configuration for 1 exhibition booth includes:
1 backdrop panel (1.8m width × 2m height)
1 display table (1.8m length × 0.75m height)
1 roll-up banner stand (0.8m width × 1.8m height)

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